

# 3A, 400V - 1000V Glass Passivated Bridge Rectifier

#### **FEATURES**

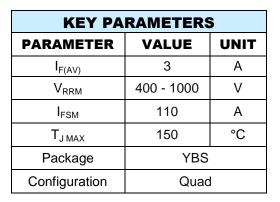
- Glass passivated junction
- Ideal for automated placement
- Reliable low cost construction utilizing molded plastic technique
- High surge current capability
- UL Recognized File # E-326854
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

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- Switching mode power supply (SMPS)
- Adapters
- TV
- Monitor

#### **MECHANICAL DATA**

- · Case: YBS
- Molding compound meets UL 94V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Packing code with suffix "G" means green compound (halogen-free)
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: As marked
- Weight: 0.22g (approximately)















ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)							
PARAMETER	SYMBOL		YBS 3004G	YBS 3005G	YBS 3006G	YBS 3007G	UNIT
Marking code on the device			YBS 3004G	YBS 3005G	YBS 3006G	YBS 3007G	
Repetitive peak reverse voltage	V	RRM	400	600	800	1000	V
Reverse voltage, total rms value		(RMS)	280	420	560	700	V
Forward current	I <sub>F(AV)</sub>		3			Α	
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub> 25°C 125°C		110 88				Α
Surge peak forward current, 1 ms single	, 25°C		220			A	
half sine-wave superimposed on rated load	I <sub>FSM</sub>	125°C	175			^	
I <sup>2</sup> t value (of a surge on-state current) <sup>(1)</sup>	l <sup>2</sup> t		50			A <sup>2</sup> s	
Junction temperature	TJ		-55 to +150			°C	
Storage temperature	T <sub>STG</sub>		-55 to +150			°C	

#### Note:

1. Pulse test with PW=8.3 ms single half sine-wave

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THERMAL PERFORMANCE						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-lead thermal resistance	$R_{\Theta JL}$	25	°C/W			
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	80	°C/W			
Junction-to-case thermal resistance	R <sub>eJC</sub>	28	°C/W			

Thermal Performance Note: Units mounted on recommended PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT	
	I <sub>F</sub> = 1.5A, T <sub>J</sub> = 25°C		0.89	1.02	V	
	I <sub>F</sub> = 3.0A, T <sub>J</sub> = 25°C	V <sub>F</sub>	0.93	1.10	V	
Forward voltage per diode (1)	I <sub>F</sub> = 1.5A, T <sub>J</sub> = 125°C		0.76	0.90	V	
	I <sub>F</sub> = 3.0A, T <sub>J</sub> = 125°C		0.82	1.00	V	
	T <sub>J</sub> = 25°C		-	5	μA	
Reverse current @ rated V <sub>R</sub> per diode <sup>(2)</sup>	T <sub>J</sub> = 125°C	l <sub>R</sub>	-	100	μA	
Junction capacitance	1 MHz, V <sub>R</sub> =4.0V	C <sub>J</sub>	33	-	pF	

#### Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION							
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING			
YBS30xxG (Note 1, 2)	RA	G	YBS	3,000 / 13" Plastic reel			

#### Notes:

- 1. "xx" defines voltage from 400V (YBS3004G) to 1000V (YBS3007G)
- 2. Whole series with green compound (halogen-free)

EXAMPLE						
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION		
YBS3007G RAG	YBS3007G	RA	G	Green compound		



#### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

Fig1. Forward Current Derating Curve

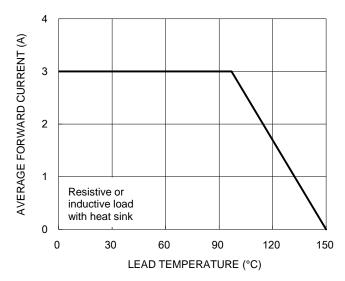


Fig2. Typical Junction Capacitance

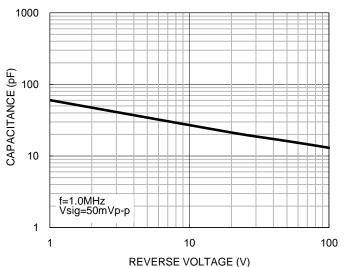


Fig3. Typical Reverse Characteristics

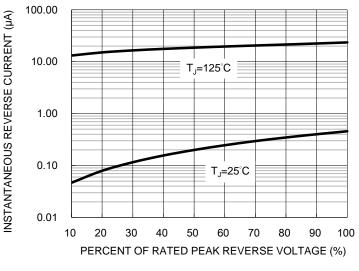
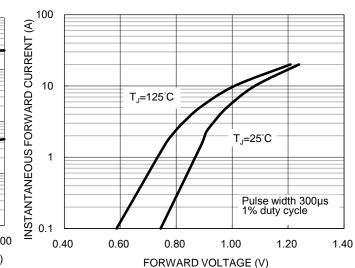


Fig4. Typical Forward Characteristics

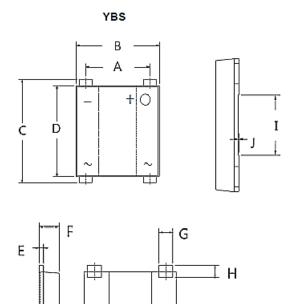


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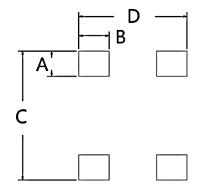


## **PACKAGE OUTLINE DIMENSIONS**



DIM	Unit	(mm)	Unit (inch)		
	Min	Max	Min	Max	
Α	5.00	5.20	0.197	0.205	
В	6.50	6.70	0.256	0.264	
С	7.90	8.60	0.311	0.339	
D	7.20	7.40	0.283	0.291	
Е	0.27	0.40	0.011	0.016	
F	1.30	1.50	0.051	0.059	
G	0.95	1.15	0.037	0.045	
Н	0.70	1.05	0.028	0.041	
	2.90	3.10	0.114	0.122	
J	0.04	0.08	0.002	0.003	

# **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	1.80	0.070
В	2.00	0.078
С	9.15	0.360
D	7.10	0.279

## **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code



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